



TSMC Honors ANSYS With "Partner Of The Year" Award

October 21, 2014

PITTSBURGH, Oct. 21, 2014 /PRNewswire/ -- TSMC has honored [ANSYS](#) (NASDAQ: ANSS) with its Open Innovation Platform® Partner of the Year 2014 award for joint development of 16-nanometer (nm) FinFET Plus design infrastructure. The award is given to TSMC OIP partners that have made significant contributions toward the development of design infrastructure for their latest process technologies. ANSYS was recognized for advanced power noise and reliability solutions that helped enable TSMC's 16nm FinFET Plus technology deployment.

ANSYS solutions for integrated circuits deliver reduced memory footprint and turnaround time to meet the demands of increased computational speed caused by the growing design complexity. TSMC and ANSYS collaborated on ANSYS®RedHawk™ and Totem™ tools in N16FF+ technology to ensure needed accuracy for static and dynamic voltage drop analysis, electromigration (EM) verification and thermal reliability sign-off of system-on-chip (SoC) and mixed-signal designs. FinFET technology is a three-dimensional transistor architecture that results in higher-performing and lower power chips used in mobile, computing and networking applications.

"ANSYS has partnered with TSMC to bring deep technical experience to address the new power and reliability challenges associated with 16nm FinFET Plus designs," said Suk Lee, TSMC senior director, Design Infrastructure Marketing Division. "We are pleased to award ANSYS with the TSMC Open Innovation Platform Partner of the Year 2014 Award for 16nm FinFET Plus development and collaboration, and look forward to continued collaborations that enable our customers to deliver products that run fast and consume less power."

"ANSYS is honored to be presented with this prestigious award from TSMC, recognizing our longstanding partnership in providing innovative solutions for power, noise and reliability sign-off of advanced manufacturing nodes," said Fares Mubarak, vice president and general manager of ANSYS. "This joint delivery of technology enables more robust integrated circuit designs and underscores our customer commitment."

About ANSYS, Inc.

ANSYS brings clarity and insight to customers' most complex design challenges through fast, accurate and reliable engineering simulation. Our technology enables organizations — no matter their industry — to predict with confidence that their products will thrive in the real world. Customers trust our software to help ensure product integrity and drive business success through innovation. Founded in 1970, ANSYS employs nearly 2,700 professionals, many of them expert in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

ANSYS also has a strong presence on the major social channels. To join the simulation conversation, please visit: www.ansys.com/Social@ANSYS

ANSYS and any and all ANSYS, Inc. brand, product, service and feature names, logos and slogans are registered trademarks or trademarks of ANSYS, Inc. or its subsidiaries in the United States or other countries. All other brand, product, service and feature names or trademarks are the property of their respective owners.

ANSS-C

Contact Media Tom Smithyman
724.820.4340
tom.smithyman@ansys.com

Investors Annette Arribas, CTP
724.514.1782
annette.arribas@ansys.com

To view the original version on PR Newswire, visit: <http://www.prnewswire.com/news-releases/tsmc-honors-ansys-with-partner-of-the-year-award-532448978.html>

SOURCE ANSYS, Inc.